

Description

The LX7220 is a digitally controlled step-down regulator IC with an integrated $22m\Omega$ high-side P-channel MOSFET and a $13m\Omega$ low-side N-channel MOSFET. It features Microsemi's proprietary constant-frequency hysteretic control engine for near-instantaneous correction to line/load transients. It does not require high-ESR output capacitors and incorporates energy-saving "PSM" (Power Save or Pulse Skip Mode) at light loads, to extend battery life in mobile applications.

The LX7220 has an I²C serial interface port for output voltage margining and monitoring if required (it can also operate in default mode). In addition, it includes robust fault monitoring functions.

The LX7220 will operate from 2.7V to 5.5V, and is available in 0.95V or 0.9V output voltages (no voltage divider is necessary). The output voltage can also be adjusted with an input voltage of 5V and external voltage divider up to 3.3V.

Features

- ♦ Constant Frequency Hysteretic Control
- ◆ Extremely Fast Line/Load Transient Response
- ♦ I²C for Output Adjustment (3.4Mbps)
- ♦ 1.2 MHz Switching Frequency
- ♦ Extremely Low-R_{DSON} MOSFETS
- ♦ Input Voltage Rail 2.7V to 5.5V
- ♦ Greater than 6A Output Current
- Default Power Save Mode for Light-Load Efficiency
- ♦ UVLO, OVP, OCP
- ♦ -40°C to +85°C Ambient Temperature
- ♦ Available in VQFN 2mm x 3mm 14L Package
- ♦ RoHS Compliant

Applications

- High Performance HDD
- Solid-State Drive
- Data Center Applications
- Raid/Host Bus Adaptors
- Optical Transceivers

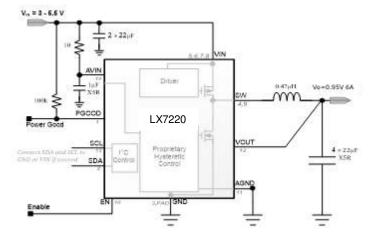
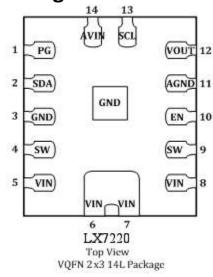


Figure 1: Typical 5V to 0.95V at 6A schematic



Pin/Ball Configuration



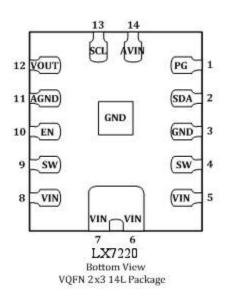


Figure 4: Pinout

Ordering Information

Temperature	Package Type	Part Marking	Part Number	<i>y</i> -Output Voltage	x-Slave Address A1A0**	Packaging Type
	Турс	MSCN		Voltage	AIAO	Турс
		7220	LX7220-03ILQ-TR		0=E0h	
		MSCP	1V7220 12U O TD		1_F2h	
		7220	LX7220-13ILQ-TR	3=0.95V	1=E2h	
		MSCR	LX7220-23ILQ-TR		2=E4h	
	VQFN 2x3	7220	LX7220-23ILQ-TK			
	14L RoHS compliant, Pb-free	MSCS	LX7220-33ILQ-TR		3=E6h	
-40°C to 85°C		7220			3-2011	Tape and Reel
-40 € 10 85 €		MSCJ	LX7220-02ILQ-TR		0=E0h	
		7220	LX7220-02ILQ-TK		0-2011	
	1 b lice	MSCK	LX7220-12ILQ-TR		1=E2h	
		7220	LX7220-12ILQ-11	2=0.9V	1-1211	
		MSCL	LX7220-22ILQ-TR	Z-0.5 V	2=E4h	
		7220	EXTEZO ZEILQ TI	_	2-6411	
		MSCM	LX7220-32ILQ-TR		3=E6h	
		7220	LA7220 SZILQ-III		J-L011	

^{*} Consult factory for other I²C slave address and set output voltage options. (LX7220-xyILQ-TR)

[&]quot;x" is the 2 LSB bits of the binary I²C slave address (0 to 3);

[&]quot;y" is the set output voltage (3 is 0.95V, 2 is 0.9V, 1 is 0.8, 0 is 0.85)

^{**}Refer to Page 12 Table 1: I2C Slave Address



Pin/Ball Description

Pin/Ball Number	Pin/Ball Designator	Description
1	PGOOD	Open Drain status output, requires external pull up resistor. This pin will go low when VOUT is outside the defined power good range, when the die is hotter than the thermal shutdown threshold, when PVIN is above the over voltage threshold, or when PVIN is below the under voltage threshold. PGOOD will go high after the last of these fault conditions clear.
10	EN	Enable for switching regulator. Force high to enable, force low to disable the IC.
13	SCL	Serial clock input for I ² C. Connect directly to GND if unused.
12	VOUT	Output voltage sense. Connect directly to output rail or resistive voltage divider output.
2	SDA	Serial data bus (bidirectional) for I ² C. Connect directly to GND if unused.
3, PAD	GND	Ground. Connect to ground plane.
11	AGND	Analog Ground. Connect to ground plane.
5,6,7,8	VIN	Input of IC and buck stage. Connect to input rail VIN (between 2.7V and 5.5V). A minimum input capacitance of one $1\mu F$ and one $22\mu F$ of X5R or better multilayer ceramic, should be placed very close to IC between this node and GND.
14	AVIN	Analog VIN voltage input pin.
4,9	SW	Switching Node. Drives the external L-C low pass filter.



Functional Block Diagram

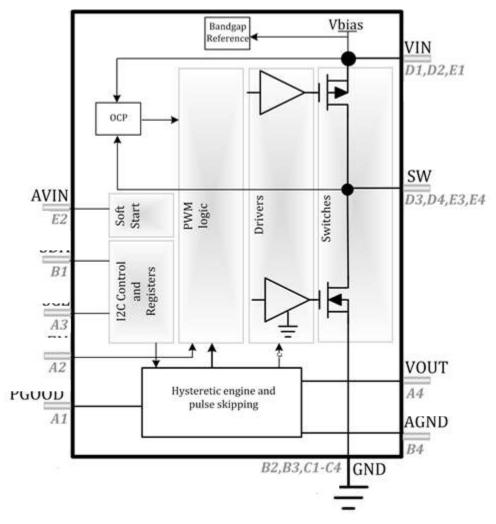


Figure 5: Block Diagram



Absolute Maximum Ratings

Performance is not necessarily guaranteed over this entire range. These are maximum stress ratings only. Exceeding these ratings, even momentarily, can cause immediate damage, or negatively impact long-term operating reliability.

	Min	Max	Units
VIN, SW to GND	-0.3	7	V
AVIN, VOUT, SDA, SCL, EN, PGOOD to GND	-0.3	7	V
SW to GND (Shorter than 50ns)	-2	7	V
Maximum Junction Temperature		150	°C
Lead Soldering Temperature (30s, reflow)		260 (+0, -5)	°C
Storage Temperature	-65	150	°C

Operating Ratings

Performance is generally guaranteed over this range as further detailed below under Electrical Characteristics.

	Min	Max	Units
VIN	2.7	5.5	V
Ambient Temperature	-40	85	°C
Output Current	0	6	A

Note: Corresponding Absolute Max Junction Temperature is 150°C.

Thermal Properties

Thermal Resistance		Тур	Units	
θ_{JA}	VQFN	50	°C/W	

Note: The θ_{JA} numbers assume no forced airflow. Junction Temperature is calculated using $T_J = T_A + (P_D \times \theta_{JA})$. In particular, θ_{JA} is a function of the PCB construction. The stated number above is for a four-layer board in accordance with JESD-51 (JEDEC).



Electrical Characteristics

The following specifications apply over the operating ambient temperature of $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$ except where otherwise noted with the following test conditions: VIN = 5V, EN = 5V, SCL = 5V, SDA = 5V, default register settings. Typical values stated, are either by design or by production testing at 25°C ambient.

Symbol	Parameter	Parameter Conditions		Тур	Max	Units
Input Volt	age					
ΙQ	Input current	I _{LOAD} = 0, PSM enabled	200	440	600	μΑ
I _{IN}	Input current at shut down	EN = GND, T _A = 25°C		0.1	14	μΑ
l _{IN_I} 2 _C	Input current I ² C shut down	VSEL(7) = low, EN = high		100	120	μΑ
UVLO	Under voltage rising threshold	VIN rising		2.6	2.89	V
UVLO _{HYST}	UVLO hysteresis			0.26		V
OVPR	Over voltage rising threshold		6.0		6.30	V
OVP _F	Over voltage falling hysteresis			0.2		V
Reference	Voltage					
T _{SS}	V _{REF} slew rate	SLEW: Ctrl2(2:1) = 01		0.8		mV/μs
THICCUP	Hiccup time	VOUT = 0.2V		9.8		ms
Output Vo	ltage			•		
	Default VOUT	VOUT=0.95V (Vin=2.7V – 5V), VSEL=40h	0.94	0.95	0.959	V
		VOUT=0.75V (Vin=2.7V – 5V), VSEL=20h	0.743	0.75	0.758	V
VOUT	VOUT I2C VSEL	VOUT=0.75V (Vin=2.7V – 5V), VSEL=20h -10°C≤ T _A ≤ 85°C	0.741	0.75	0.759	V
		VOUT=1.197V (Vin=2.7V – 5V), VSEL=7Fh	1.185	1.197	1.2	V
	Line regulation	VIN from 3V to 5.5V, I _{LOAD} = 1A. Note 1		0.1		%
	Load regulation	I _{LOAD} = 0A to 5A. Note 1		-0.23		%/A
	VOUT input current			0	1	μΑ
Vouv	VOUT under voltage threshold	VOUT below this threshold will initiate a hiccup sequence	77	82	85	%V _{REF}
SW	•	•		•		



Symbol	Parameter	Conditions	Min	Тур	Max	Units
R _{DSON_H}	High side on resistance	VIN = 5V		22		mΩ
R _{DSON_L}	Low side on resistance	VIN = 5V		13		mΩ
ОСР	Current limit	Note 1	7.5	8.5	10.0	Α
T _{SH}	Thermal shut down threshold	Note 1		150		°C
T _H	Hysteresis	Note 1		20		°C
F _{SW}	PWM switching frequency		1.0	1.2	1.4	MHz
R _{SWDISC}	SW discharge resistance	EN = low; Discharge: Ctrl2(4) = 1	80	200	1400	Ω
EN, SDA (a	s input), SCL					
V _{IH}	Input high		1.1			V
V _{IL}	Input low				0.4	V
V_{H}	Hysteresis		0.05	0.15		V
III	Input current			0	1.1	μΑ
V_{OL}	Low level output voltage	Logic0 output voltage, Isink=2mA(Note 1)	0		0.2*V DD	V
I _{OL}	Low level output current	Vol=0.4V(Note 1)	3			mA
PGOOD			•	-	•	
V _{PG90}	PGOOD VOUT lower threshold	VOUT rising, percentage of V _{REF}	82	85	88	%V _{REF}
V _{PG110}	PGOOD VOUT upper threshold	VOUT falling, percentage of V _{REF}	105	110	115	%V _{REF}
V_{PGHY}	Hysteresis	Percentage of V _{REF}		5		%V _{REF}
PG _{RDSON}	PGOOD pull down resistance			13	20	Ω
	PGOOD leakage current			0	1	μΑ
	PGOOD delay	PGOOD rising edge delay	27	45	69	ms
7 Bit DAC						
	Differential linearity	Monotonicity assured by design			0.8	LSB

Note 1: Guaranteed by design.

LX7220



2.7V to 5.5V, 6A Constant Frequency Hysteretic Synchronous Buck Regulator with I²C Production Data Spec

Application Specifics

I _{OUT} = 2.0A, VCC = 5V, VOUT = 3.3V	95%	
I _{OUT} = 4.0A, VCC = 5V, VOUT = 0.8V, Inductor(IHLP-2020CZ-01)	>84%	
I _{OUT} = 4.0A, VCC = 5V, VOUT = 0.9V, Inductor(SPM5015)	>83%	
100mA \Leftrightarrow 4A, 1A/2us, C _{LOAD} = 4 x 22μF ceramic caps, 0.47μH	Peak to	
inductor. Step Duration 1us-50us	peak<80mV	
IHLP2020CZ(DCR = $6.7m\Omega$, IDC = 12.2A, ISAT = 16A)	0.47.14	
SPM5015(DCR = 16.3 m Ω , IDC = 7 A, ISAT = 13.8 A)	0.47μH	
6 2V VED	4v22uE	
0.5V, A3K	4x22μF	
Iout-5A VCC-5V VOLIT-1V Inductor(SDM5015)	<200mVpp	
10ut-3A, VCC-3V, VOOT-1V, Illudctor(3F1V13013)	<50mVpp	
VCC-5V Rises-50 Ohms Closs-200uE caramic cans Enable		
• • •	<175mA _{PEAK}	
1 – 300112 3070 daty cycle		
	I_{OUT} = 4.0A, VCC = 5V, VOUT = 0.8V, Inductor(IHLP-2020CZ-01) I_{OUT} = 4.0A, VCC = 5V, VOUT = 0.9V, Inductor(SPM5015) 100mA \Leftrightarrow 4A, 1A/2us, C _{LOAD} = 4 x 22μF ceramic caps, 0.47μH inductor. Step Duration 1us-50us IHLP2020CZ(DCR = 6.7m Ω , IDC = 12.2A, ISAT = 16A)	



I²C Timing Specifications

Symbol	(max) (*Note2)		C _b = 400 pF		Unit		
			Min	Max	Min	Max	
f _{SCHL}	SCL clock frequency		0	3.4	0	0.4	MHz
t _{SU;STA}	Set-up time for a repeated START condition		160	-	600	-	ns
t _{HD;STA}	Hold time (repeated) START condition		160	-	600	-	ns
t _{LOW}	LOW period of the SCL clock		160	-	1300	-	ns
t _{HIGH}	HIGH period of the SCL		600	-	ns		
t _{SU;DAT}	Data set-up time 10 -		100	-	ns		
t _{HD;DAT}	Data hold time		0	70	0	-	ns
t _{rCL}	Rise time of SCL signal		10	40	20*0.1C _b	300	ns
Rise time of SCL signal after a repeated START condition and after an acknowledge bit			10	80	20*0.1C _b	300	ns
t _{fCL}	Fall time of SCL signal		10	40	20*0.1C _b	300	ns
t _{rDA}	Rise time of SDA signal		10	80	20*0.1C _b	300	ns
t _{fDA}	Fall time of SDA signal		10	80	20*0.01Cb	300	ns
t _{SU;STO}	Set-up time for STOP condition		160	-	600	-	ns
t _{BUF}	Bus free time between a STOP and START condition		160	-	1300	-	ns
t _{VD;DAT}	Data valid time		-	160	-	900	ns
t _{VD;ACK}	Data valid acknowledge time		-	160	-	900	ns
C _b	Capacitive load for each bus line	SDA and SCL lines	-	100		400	pF

Note 1: All values referred to $V_{IH}(min)$ and $V_{IL}(max)$ levels of I/O stages table. Note 2: Loads in excess of 100pF will restrict bus operation speed below 3.4MHz



Operation Theory

Basic Operation

The LX7220 compares VOUT voltage to an internal reference, V_{REF} . When VOUT is lower than V_{REF} , the upper switch turns on and the lower switch turns off. When VOUT is higher than V_{REF} , the upper switch turns off and the lower switch turns on. An internal ramp helps to keep the switching frequency constant over a wide range of output capacitor values and parasitic components (i.e. ESR, ESL). In addition, a frequency control loop keeps the switching frequency constant during continuous conduction mode.

At light loads, if enabled, the converter automatically reduces the switching frequency and enters discontinuous conduction to optimize efficiency while ensuring low VOUT ripple voltage.

An integrated I²C bus interface, operating up to 3.4Mbps, adds the following use programmability to the converter:

- 1. On the fly programming of the output voltage in 4.7mV increments.
- 2. Enable / Disable the regulator.
- 3. Allow PSM or limit operation to only PWM mode.
- 4. Set the V_{REF} slew rate.
- 5. Switch node slew rate control.

Setting the Output Voltage

The output voltage is set with the reference voltage and how the VOUT pin (12) is connected to the output. With a direct connection (i.e. See Figure 2), the reference voltage equals the output voltage. When the VOUT pin (12) is connected to a resistor divider (i.e. See Figure 3), this also determines the output voltage. At startup, the reference voltage is determined by the parts number "y" parameter (i.e. LX7220-xylLQ). "y" sets the output voltage (3 is 0.95V, 2 is 0.9V). After startup, the reference voltage can be programmed with the I²C bus VSEL register value.

$$V_{REF} = 0.6V + N_{SEL} \cdot 0.0046875V \tag{2}$$

Where N_{SEL} is the decimal value of the 7 VSEL bits. The output voltage is determined as follows:

$$V_{OUT} = V_{REF} \times \left(1 + \frac{R_{TOP}}{R_{BOTTOM}}\right) \tag{3}$$

 R_{TOP} is the resistor connected from VOUT pin to output, R_{BOTTOM} is the resistor connected from VOUT pin to GND.

Startup

If the LX7220 is enabled, when VIN rises above the UVLO threshold, the regulator will initiate a startup sequence. The serial port registers are initialized to their default values and all internal bias voltages and currents are allowed to stabilize. V_{REF} then ramps up from 0V to the default voltage at the default slew rate. At the end of the ramp time, PGOOD is allowed to go high after VOUT has reached the PGOOD rising threshold. During the ramp time, the LX7220 switches to PSM to allow discontinuous operation. This switchover is independent of the MODE bit setting.



Operation Theory (Continued)

Over Current Protection

The LX7220 protects against all types of short circuit conditions. Cycle by cycle over current protection turns off the upper switch when the current exceeds the OCP threshold. When this occurs, the upper switch is held off for at least 350ns before being allowed to turn on again. After startup, if VOUT drops below the VOUT under voltage threshold, a hiccup sequence will be initiated where both output switches are shut off for 6.5ms before initiating another soft start cycle. This protects against a crowbar short circuit. The VOUT under voltage detection is not active during start up.

Positive Voltage Transitions

After the initial startup sequence, the output voltage can be programmed to a new value by programming the VSEL register bits and then asserting the GO bit. V_{REF} will transition to the new value at the programmed slew rate. The PGOK monitor bit is deasserted during the V_{REF} ramp time, or when VOUT is outside the error envelope.

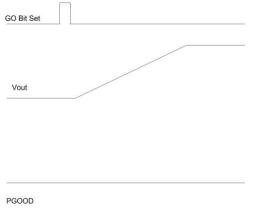


Figure 18: Positive Voltage Transition

Negative Voltage Transitions

A negative voltage transition occurs when a lower output voltage is programmed into the VSEL register, and initiated by asserting the GO bit. In PSM, the LX7220 will not discharge the output filter capacitor.

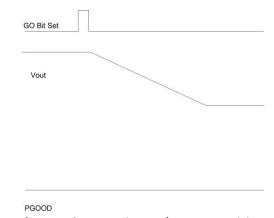


Figure 19: Negative Voltage Transition

Enabling Regulator from I²C Bus

In addition to the EN pin, the regulator can be enabled and disabled via the I²C bus by programming the control register. During disable, the regulator and most of the support circuitry is turned off. However, the I²C bus circuitry is still active and may be programmed.

Switch Node rise rate adjustment

The LX7220 can be programmed to operate in a lower emissions mode by slowing down the switch node rise rate. In this mode, the switch node rise rate will slow down 25%, reducing the switching frequency harmonic content.



I²C Interface

I²C Port Functional Description

- Simple two wire, bidirectional, serial communication port.
- Multiple devices on same bus speeds from 400Kbps (FS-Mode) to 3.4Mbps (HS-Mode).
- SOC Master controls bus.
- Device listens for the unique address that precedes data.

General I²C Port Description

The LX7220 includes an I²C compatible serial interface, using two dedicated pins: SCL and SDA for I²C clock and data respectively. Each line is externally pulled up to a logic voltage when they are not being controlled by a device on the bus. The LX7220 interface acts as an I²C slave that is clocked by the incoming SCL clock. The LX7220 I²C port will support both the Fast mode (400kHz max) and typically the High Speed mode (3.4MHz max). The data on the SDA line must be stable during the HIGH period of the clock signal (SCL). The state of the SDA line can only be changed when SCL is LOW (except for start, stop, and restart).

Register Map

The LX7220 has five 8-bit user-accessible registers. See Control Register Bit Definition.

Slave Address

In the table below, the A1 and A0 are the binary value of the address given in the ordering information for the "x" value shown on page 3.

7	6	5	4	3	2	1	0
1	1	1	0	0	A1	Α0	R/W

Table 1: I²C Slave Address

START and STOP Commands

When the bus is idle, both SCL and SDA must be high except in the power up case where they may be held high or low during the system power up sequence.

The STX SOC (bus master) signals START and STOP bits signify the beginning and the end of the I²C transfer. The START condition is defined as the SDA signal transitioning from HIGH to LOW while the SCL line is HIGH. The STOP condition is defined as the SDA transitioning from LOW to HIGH while the SCL is HIGH. The STX SOC acts as the I²C master and always generates the START and STOP bits. The I²C bus is considered to be busy after START condition and free after STOP condition. During data transfer, STX SOC master can generate repeated START conditions. The START and the repeated START conditions are functionally equivalent.



I²C Interface (Continued)

Data Transfers

Data is transferred in 8 bit bytes by SDA with the MSB transferred first. Each byte of data has to be followed by an acknowledge (ACK) bit. The acknowledged related clock pulse is generated by the master. The acknowledge occurs when the transmitter master releases the SDA line to a high state during the acknowledge clock. The SDA line must be pulled down by the receiver slave during the 9th clock pulse to signify acknowledgment. A receiver slave which has been addressed must generate an acknowledgement ("ACK") after each byte has been received.

After the START condition, the STX SOC (I²C) master sends a chip address. The standard I²C address is seven bits long. Making the eighth bit a data direction bit (R/W). For the eighth bit (LSB), a "0" indicates a WRITE and a "1" indicates a READ. (For clarification, communications are broken up into 9-bit segments, one byte followed by one bit for acknowledging.) The second byte selects the register to which the data will be written. The third byte contains data to write to the selected register.

When a receiver slave doesn't acknowledge the slave address, the data line must be left HIGH by the slave. The master can then generate a STOP command to abort the transfer. If a slave receiver does acknowledge the slave address but, sometime later in the transfer cannot receive any more data bytes, the master must again abort the transfer. This is indicated by the slave generating the not acknowledge on the first byte to follow.

The slave leaves the data line HIGH and the master generates the STOP command. The data line is also left high by the slave and master after a slave has transmitted a byte of data to the master in a read operation, but this is a not acknowledge that indicates that the data transfer is successful.

Data Transfer Timing for Write Commands

In order to help assure that bad data is not written into the part, data from a write command is only stored after a valid STOP command has been performed.

I²C Electrical Characteristics

The minimum HIGH and LOW periods of the SCL clock specified the I²C Timing Specification table determine the maximum bit transfer rates of, 400 kbits/s for Fast-mode devices, and 3.4 Mbits/s for HS-mode Plus. Devices must be able to follow transfers at their own maximum bit rates, either by being able to transmit or receive at that speed or by applying the I²C clock synchronization procedure, which will force the master into a wait state and stretch the LOW period of the SCL signal. Of course, in the latter case the bit transfer rate is reduced.

Figures 22 and Figure 23 show all timing parameters for the HS & FS-mode timing. The 'normal' START condition S does not exist in HS-mode. Timing parameters for Address bits, R/W bit, Acknowledge bit and DATA bits are all the same. Only the rising edge of the first SCL clock signal after an acknowledge bit has a larger value because the external Rp has to pull-up SCL without the help of the internal current-source.



I²C Interface (Continued)

The HS & FS-mode timing parameters for the bus lines are specified in the I²C Timing Specification Table. The minimum HIGH and LOW periods and the maximum rise and fall times of the SCL clock signal determine the highest bit rate.

With an internally generated SCL signal with LOW and HIGH level periods of 200ns and 100ns respectively, an HS-mode master fulfills the timing requirements for the external SCL clock pulses (taking the rise and fall times into account) for the maximum bit rate of 3.4 Mbit/s. So a basic frequency of 10 MHz, or a multiple of 10 MHz, can be used by an HS-mode master to generate the SCL signal. There are no limits for maximum HIGH and LOW periods of the SCL clock, and there is no limit for a lowest bit rate.

Timing parameters are independent for capacitive load up to 100 pF for each bus line allowing the maximum possible bit rate of 3.4 Mbit/s. At a higher capacitive load on the bus lines, the bit rate decreases gradually. The timing parameters for a capacitive bus load of 400 pF are specified in I²C Timing Specification Table, allowing a maximum bit rate of 1.7 Mbit/s. For capacitive bus loads between 100pF and 400 pF, the timing parameters must be interpolated linearly. Rise and fall times are in accordance with the maximum propagation time of the transmission lines SDA and SCL to prevent reflections of the open ends.



Figure 20: Write Protocol



Figure 21: Read Protocol



I²C Interface (Continued)

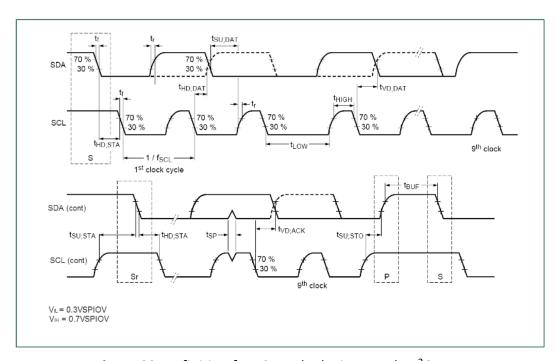


Figure 22: Definition for FS-Mode devices on the I²C Port

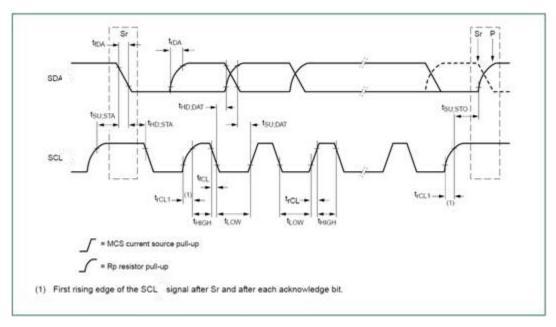


Figure 23: Timing definition for HS-mode devices on the I²C Port



I²C Interface (Continued)

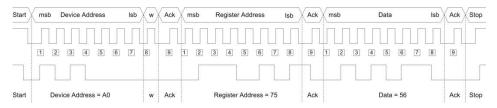


Figure 24: Write Cycle Diagram

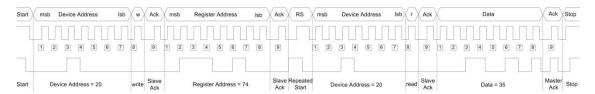


Figure 25: Read Cycle Diagram

Control Register Bit Definition

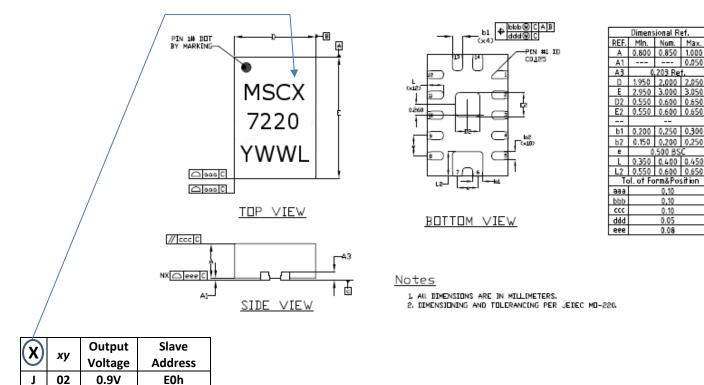
Bit	Name	Value	Description				
Status	s, Address 00h						
7:3	Reserved						
2	ОСР		Latched to 1 if the over current limit is reached. Write a "1" to reset the status flag.				
1	ОТР		Latched to 1 if an over temperature event occurs. Write a "1" to reset the status flag.				
0	FB_UVLO		Latched to 1 if a FB_UVLO event occurs. Write a "1" to reset the status flag.				
Vsel,	Address 01h, (aka da	ic)					
7	ENI	1-d	Device enabled.				
/	EN	0	Device disabled.				
6:0	VCEL[6:0]		7-bit DAC value to set V _{REF} . The default value is determined by the				
0.0	VSEL[6:0]		part ordering code.				
Ctrl1,	Ctrl1, Address 02h, (aka reg2)						
7:6	Reserved	00-d					



Bit	Name	Value	Description	
5	ctrl1	1-d	TBD	
4	DIV DIC	1	45ms delay on PGOOD is enabled.	
4	DLY_DIS	0-d	Disable 45ms delay on PGOOD.	
3	Dosomiad	1-d		
3	Reserved	0		
2	Reserved	1-d		
2	Reserveu	0		
1	Reserved	1-d		
1	Reserved	0		
0	MODE	0	PWM mode only – NO PSM.	
U	MODE	1-d	Power Saving Mode – allows discontinuous conduction.	
Vendo	or ID, Address 03h (F	Read Only)		
7:4	VID[3:0]	0010	Microsemi Vendor ID.	
3:2	A1A0	00	Designates the slave address version. These bits will correspond to	
5.2	AIAU	00	the two LSB bits.	
1:0	VOUT	11	The default output voltage is 0.95V.	
Ctrl2,	Address 04h, (aka re	eg4)		
7:6	Reserved			
		1	1	Writing to this bit starts a VOUT transition regardless of its initial
5	GO	1	value.	
		0-d	The VOUT is ramped to the default VSEL Value.	
4	Discharge	1	When the regulator is disabled, the output voltage is discharged through the SW pin.	
		0-d	When the regulator is disabled, the output voltage Is not discharged.	
	DCOV	1	Is high when output is in regulation and V _{REF} has stabilized.	
3	PGOK (read only)	0	Is low during an output voltage transition or when the output is not in regulation.	
		01-d	V _{REF} slews at 0.8mV/μs.	
2:1	SLEW	10	V _{REF} slews at 2.2mV/μs.	
		11	V_{REF} slews at 8.4mV/ μ s.	
0	Reserved			
<u> </u>	1			

Note: -d is the default value at startup.





Package Dimensions

K

L

Μ

Ν

Ρ

R

12

22

32

03

13

23

33

0.9V

0.9V

0.9V

0.95V

0.95V

0.95V

0.95V

E2h

E4h

E6h

E0h

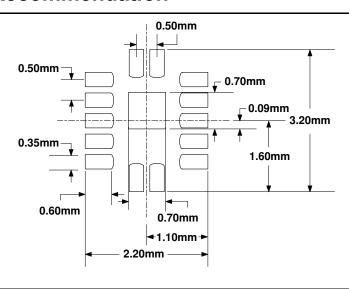
E2h

E4h

E6h



Land Pattern Recommendation



LQ 14-Pin VQFN Package Land Pattern

Disclaimer

This PCB land pattern recommendation is based on information available to Microsemi by its suppliers. The actual land pattern to be used could be different depending on the materials and processes used in the PCB assembly, end user must account for this in their final layout. Microsemi makes no warranty or representation of performance based on this recommended land pattern

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